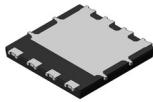


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

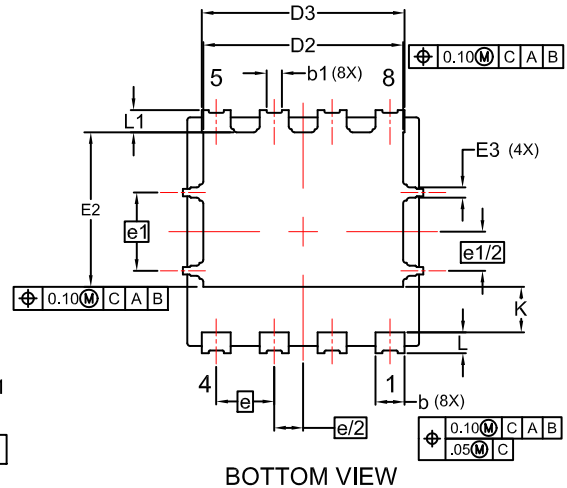
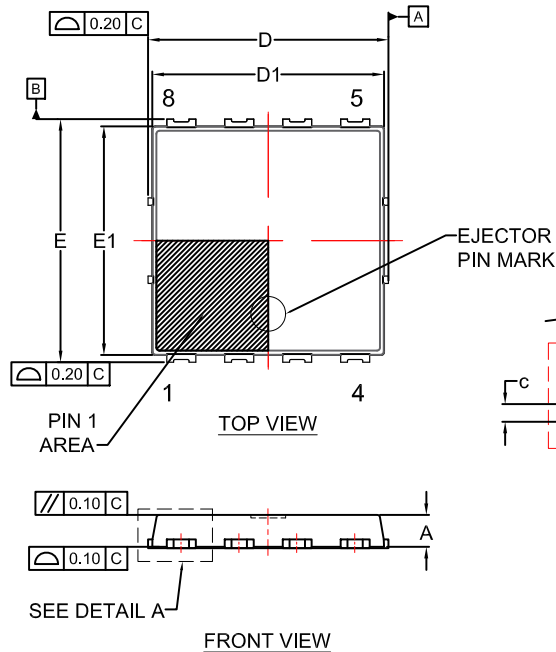
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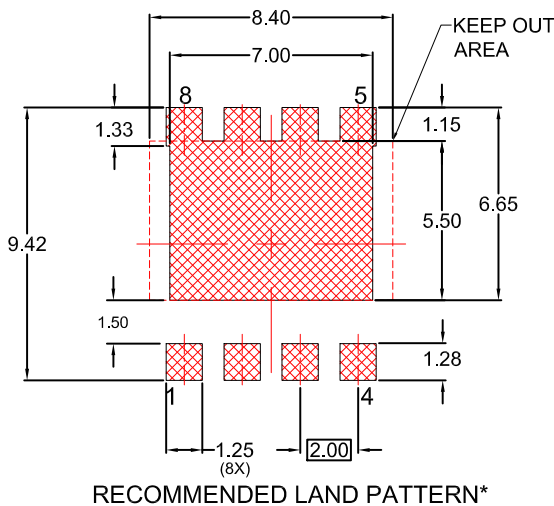
**DFNW8 8.3x8.4, 2P**  
CASE 507AP  
ISSUE C

DATE 11 JUN 2020



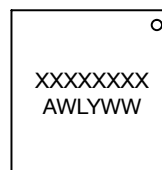
## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

## GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot Code  
Y = Year Code  
WW = Work Week Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

| DIM  | MILLIMETERS |      |      |
|------|-------------|------|------|
|      | MIN.        | NOM. | MAX. |
| A    | 1.00        | 1.10 | 1.20 |
| A1   | 0.00        | —    | 0.05 |
| b    | 0.90        | 1.00 | 1.10 |
| b1   | 0.43        | 0.53 | 0.63 |
| c    | 0.23        | 0.28 | 0.33 |
| D    | 8.20        | 8.30 | 8.40 |
| D1   | 7.90        | 8.00 | 8.10 |
| D2   | 6.80        | 6.90 | 7.00 |
| D3   | 6.90        | 7.00 | 7.10 |
| E    | 8.30        | 8.40 | 8.50 |
| E1   | 7.80        | 7.90 | 8.00 |
| E2   | 5.24        | 5.34 | 5.44 |
| E3   | 0.25        | 0.35 | 0.45 |
| e    | 2.00 BSC    |      |      |
| e/2  | 1.00 BSC    |      |      |
| e1   | 2.70 BSC    |      |      |
| e1/2 | 1.35 BSC    |      |      |
| K    | 1.50        | 1.57 | 1.70 |
| L    | 0.64        | 0.74 | 0.84 |
| L1   | 0.67        | 0.77 | 0.87 |
| Θ    | 0°          | —    | 12°  |

|                         |                          |   |
|-------------------------|--------------------------|---|
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| <b>DESCRIPTION:</b>     | <b>DFNW8 8.3x8.4, 2P</b> | <b>PAGE 1 OF 1</b>  |

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